

RoHS Compliant Product  
A suffix of "-C" specifies halogen & lead-free

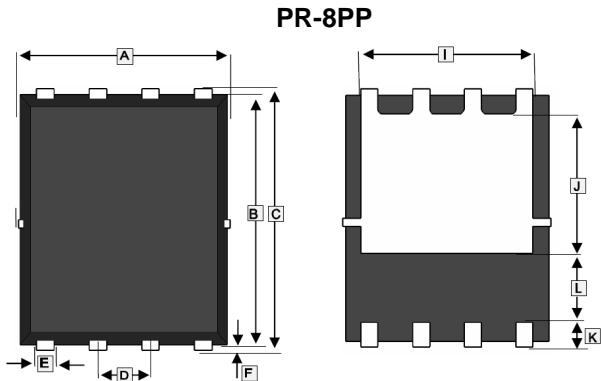
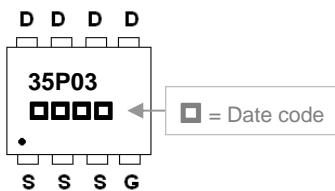
## DESCRIPTION

The SPR35P03 provide the designer with the best combination of fast switching, ruggedized device design, low on-resistance and cost-effectiveness. The PR-8PP package is universally preferred for all commercial-industrial surface mount applications and suited for low voltage applications such as DC/DC converters.

## FEATURES

- Lower Gate Charge
- Simple Drive Requirement
- Fast Switching Characteristic

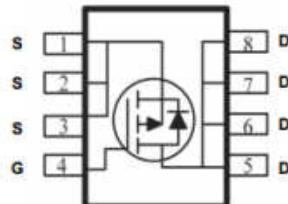
## MARKING



REF.	Millimeter		REF.	Millimeter	
	Min.	Max.		Min.	Max.
A	4.9	5.1	G	0.8	1.0
B	5.7	5.9	H	0.254	Ref.
C	5.95	6.2	I	4.0	Ref.
D	1.27	BSC.	J	3.4	Ref.
E	0.35	0.49	K	0.6	Ref.
F	0.1	0.2	L	1.4	Ref.

## PACKAGE INFORMATION

Package	MPQ	Leader Size
PR-8PP	3K	13 inch



## ABSOLUTE MAXIMUM RATINGS ( $T_A=25^\circ\text{C}$ unless otherwise specified)

Parameter	Symbol	Rating	Unit
Drain-Source Voltage	$V_{DS}$	-30	V
Gate-Source Voltage	$V_{GS}$	$\pm 20$	V
Continuous Drain Current <sup>1</sup> @ $V_{GS}=10\text{V}$	$I_D$	-35	A
		-22	A
		-8.5	A
		-6.8	A
Pulsed Drain Current <sup>2</sup>	$I_{DM}$	-70	A
Single Pulse Avalanche Energy <sup>3</sup>	EAS	135	mJ
Avalanche Current	$I_{AS}$	-30	A
Total Power Dissipation <sup>4</sup>	$P_D$	37.5	W
Operating Junction & Storage Temperature	$T_J, T_{STG}$	-55~150	°C
Thermal Resistance Rating			
Thermal Resistance Junction-Ambient <sup>1</sup> (Max).	$R_{\theta JA}$	62	°C / W
Thermal Resistance Junction-Case <sup>1</sup> (Max).	$R_{\theta JC}$	3.33	°C / W

**ELECTRICAL CHARACTERISTICS** ( $T_J = 25^\circ\text{C}$  unless otherwise specified)

Parameter	Symbol	Min.	Typ.	Max.	Unit	Test Conditions
<b>Static</b>						
Drain-Source Breakdown Voltage	$BV_{DSS}$	-30	-	-	V	$V_{GS}=0$ , $I_D = -250\mu\text{A}$
Gate-Threshold Voltage	$V_{GS(\text{th})}$	-1	-	-2.5	V	$V_{DS}=V_{GS}$ , $I_D = -250\mu\text{A}$
Forward Tranconductance	$g_{fs}$	-	5	-	S	$V_{DS} = -5\text{V}$ , $I_D = -10\text{A}$
Gate-Source Leakage Current	$I_{GSS}$	-	-	$\pm 100$	nA	$V_{GS} = \pm 20\text{V}$
Drain-Source Leakage Current	$I_{DSS}$	-	-	-1	$\mu\text{A}$	$V_{DS} = -24\text{V}$ , $V_{GS}=0$ , $T_J=25^\circ\text{C}$
		-	-	-5		$V_{DS} = -24\text{V}$ , $V_{GS}=0$ , $T_J=55^\circ\text{C}$
Static Drain-Source On-Resistance <sup>2</sup>	$R_{DS(\text{ON})}$	-	-	27	$\text{m}\Omega$	$V_{GS} = -10\text{V}$ , $I_D = -15\text{A}$
		-	-	35		$V_{GS} = -4.5\text{V}$ , $I_D = -10\text{A}$
Gate Resistance	$R_g$	-	18	26	$\Omega$	$f = 1.0\text{MHz}$
Total Gate Charge	$Q_g$	-	12.5	-	$\text{nC}$	$I_D = -15\text{A}$ $V_{DS} = -15\text{V}$ $V_{GS} = -4.5\text{V}$
Gate-Source Charge	$Q_{gs}$	-	5.4	-		
Gate-Drain ("Miller") Change	$Q_{gd}$	-	5	-		
Turn-on Delay Time <sup>2</sup>	$T_{d(on)}$	-	4.4	-	$\text{nS}$	$V_{DD} = -15\text{V}$ $I_D = -15\text{A}$ $V_{GS} = -10\text{V}$ $R_G = 3.3\Omega$
Rise Time	$T_r$	-	11.2	-		
Turn-off Delay Time	$T_{d(off)}$	-	34	-		
Fall Time	$T_f$	-	18	-		
Input Capacitance	$C_{iss}$	-	1345	-	$\text{pF}$	$V_{GS} = 0$ $V_{DS} = -15\text{V}$ $f = 1.0\text{MHz}$
Output Capacitance	$C_{oss}$	-	194	-		
Reverse Transfer Capacitance	$C_{rss}$	-	158	-		
<b>Guaranteed Avalanche Characteristics</b>						
Single Pulse Avalanche Energy <sup>5</sup>	EAS	33.7	-	-	mJ	$V_{DD} = -25\text{V}$ , $L = 0.1\text{mH}$ , $I_{AS} = -15\text{A}$
<b>Source-Drain Diode</b>						
Diode Forward Voltage <sup>2</sup>	$V_{SD}$	-	-	-1.2	V	$I_S = -1\text{A}$ , $V_{GS} = 0\text{V}$
Continuous Source Current <sup>1,6</sup>	$I_S$	-	-	-35	A	$V_G = V_D = 0$ , Force Current
Pulsed Source Current <sup>2,6</sup>	$I_{SM}$	-	-	-70	A	
Reverse Recovery Time	$t_{rr}$	-	12.4	-	$\text{nS}$	$ I_F  = -15\text{A}$ , $dI/dt = 100\text{A}/\mu\text{s}$ , $T_J = 25^\circ\text{C}$
Reverse Recovery Charge	$Q_{rr}$	-	5	-	nC	

Note:

- The data tested by surface mounted on a 1 inch<sup>2</sup> FR-4 board with 2OZ copper,  $\leq 10\text{sec}$ ,  $125^\circ\text{C}/\text{W}$  at steady state
- The data tested by pulsed, pulse width  $\leq 300\mu\text{s}$ , duty cycle  $\leq 2\%$
- The EAS data shows Max. rating. The test condition is  $V_{DD} = -25\text{V}$ ,  $V_{GS} = -10\text{V}$ ,  $L = 0.1\text{mH}$ ,  $I_{AS} = -30\text{A}$
- The power dissipation is limited by  $150^\circ\text{C}$  junction temperature
- The Min. value is 100% EAS tested guarantee.
- The data is theoretically the same as ID and IDM, in real applications, should be limited by total power dissipation.

## CHARACTERISTIC CURVES

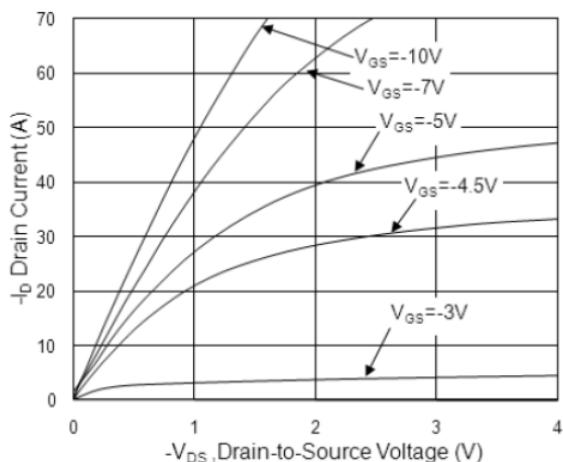


Fig.1 Typical Output Characteristics

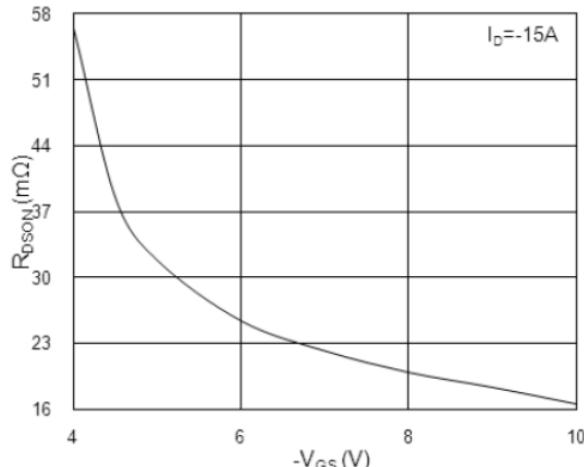


Fig.2 On-Resistance v.s Gate-Source

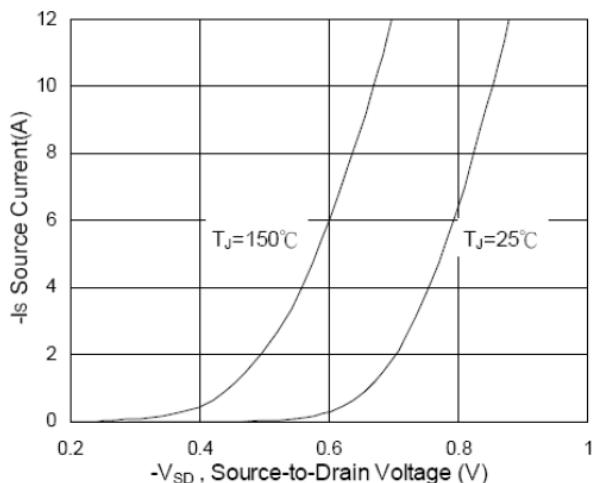


Fig.3 Forward Characteristics of Reverse

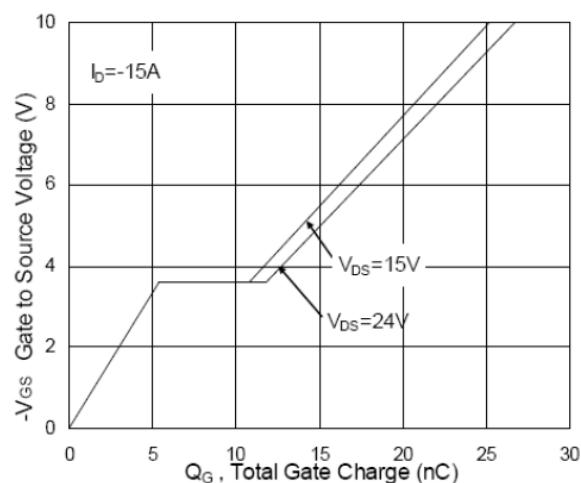


Fig.4 Gate-Charge Characteristics

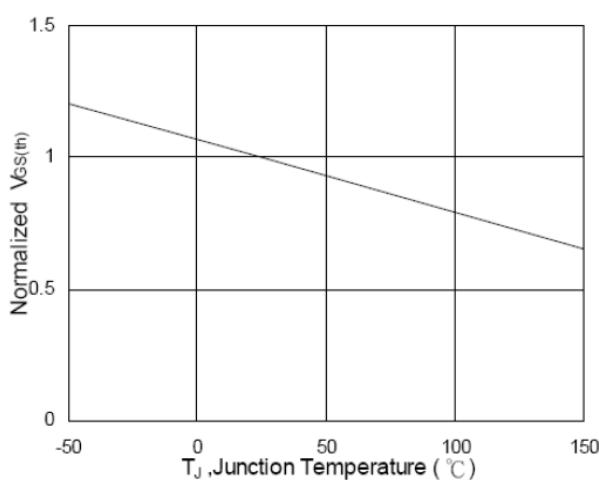


Fig.5 Normalized  $V_{GS(th)}$  v.s  $T_J$

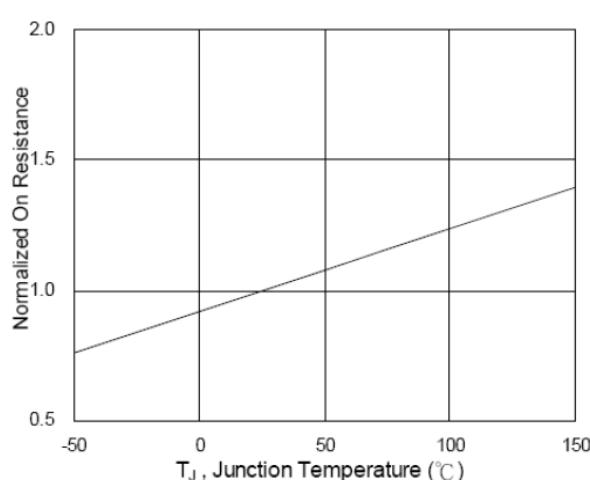


Fig.6 Normalized  $R_{DS(on)}$  v.s  $T_J$

## CHARACTERISTIC CURVES

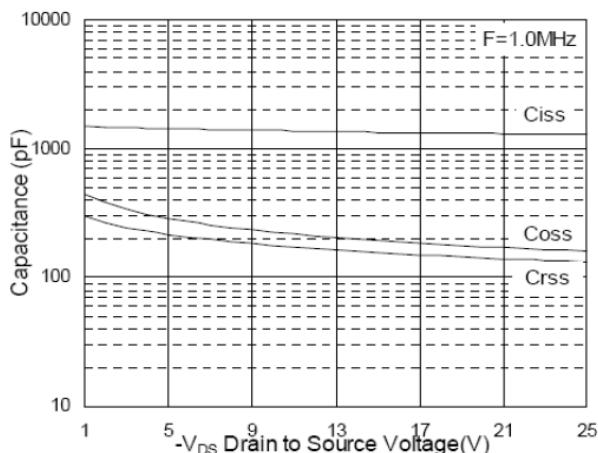


Fig.7 Capacitance

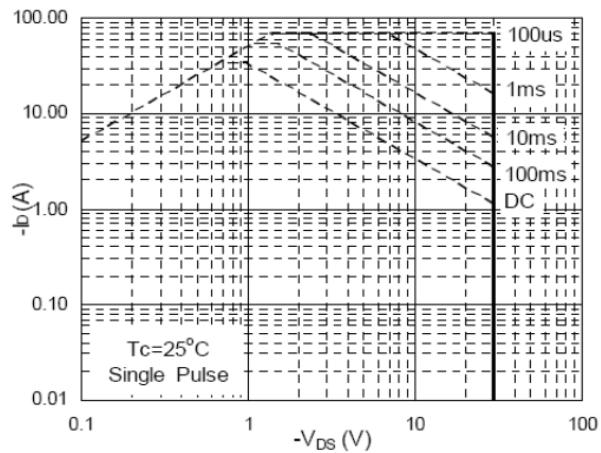


Fig.8 Safe Operating Area

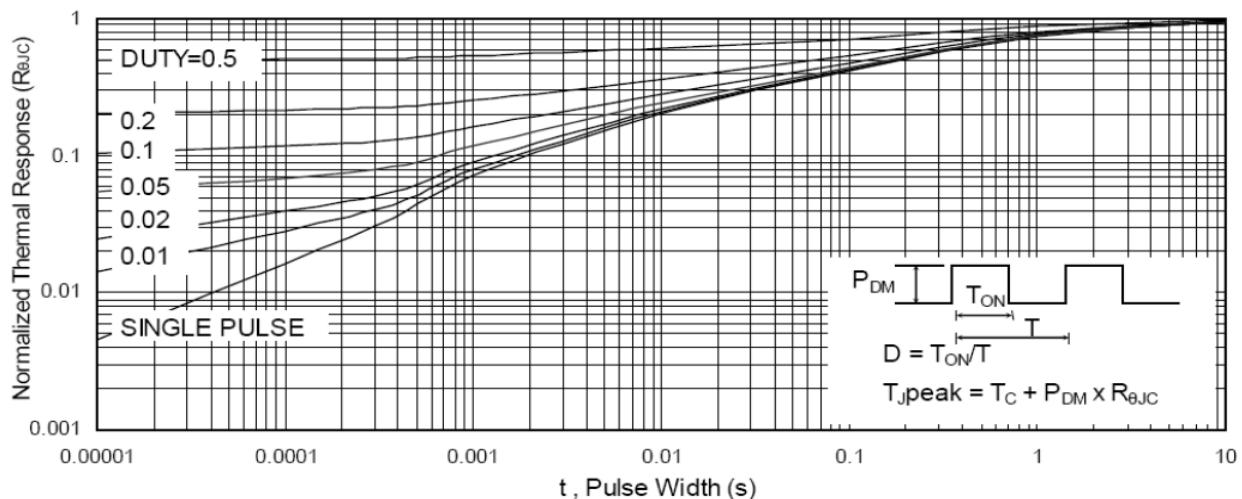


Fig.9 Normalized Maximum Transient Thermal Impedance

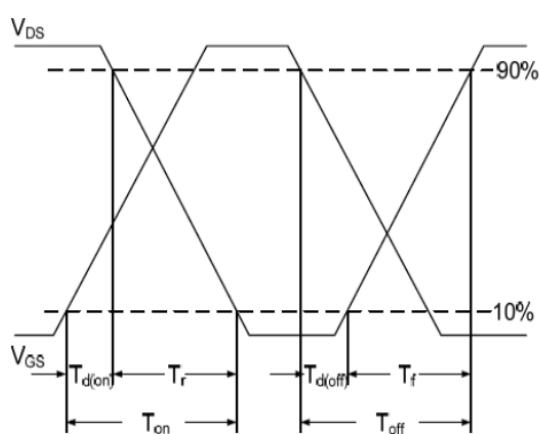


Fig.10 Switching Time Waveform

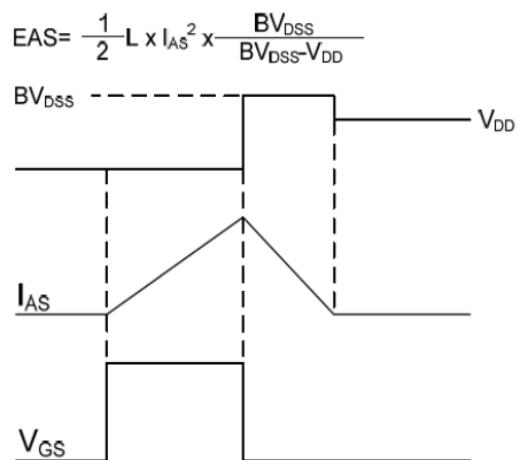


Fig.11 Unclamped Inductive Switching Waveform